

	<h1>Tentative</h1>	<b>DMA364A1</b>	
		Total pages	page

# DMA364A1

Silicon PNP epitaxial planar type (Tr1)

Silicon PNP epitaxial planar type (Tr2)

For digital circuits

Marking Symbol : E9

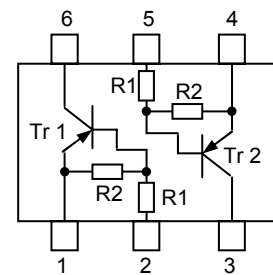
Package Code : SSSMini6-F2-B

## Absolute Maximum Ratings $T_a = 25\text{ }^\circ\text{C}$

Parameter		Symbol	Rating	Unit
Tr1	Collector-base voltage (Emitter open)	VCBO	-50	V
	Collector-emitter voltage (Base open)	VCEO	-50	V
Tr2	Collector current	IC	-80	mA
Overall	Total power dissipation *1	PT	125	mW
	Junction temperature	Tj	150	$^\circ\text{C}$
	Storage temperature	Tstg	-55 to +150	$^\circ\text{C}$

Note: 1. \*1 Measuring on substrate at 17 mm × 10 mm × 1 mm

## Internal Connection



Resistance value	R1	10	k $\Omega$
	R2	10	k $\Omega$

## Pin name

1.	Emitter(Tr1)	4.	Emitter(Tr2)
2.	Base(Tr1)	5.	Base(Tr2)
3.	Collector(Tr2)	6.	Collector(Tr1)

## Electrical Characteristics $T_a = 25\text{ }^\circ\text{C} \pm 3\text{ }^\circ\text{C}$

Tr1,Tr2

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	VCBO	IC = -10 $\mu\text{A}$ , IE = 0	-50			V
Collector-emitter voltage (Base open) *1	VCEO	IC = -2 mA, IB = 0	-50			V
Collector-base cutoff current (Emitter open)	ICBO	VCB = -50 V, IE = 0			-0.1	$\mu\text{A}$
Collector-emitter cutoff current (Base open)	ICEO	VCE = -50 V, IB = 0			-0.5	$\mu\text{A}$
Emitter-base cutoff current (Collector open)	IEBO	VEB = -6 V, IC = 0			-0.5	mA
Forward current transfer ratio	hFE	VCE = -10 V, IC = -5 mA	35			-
Collector-emitter saturation voltage	VCE(sat)	IC = -10 mA, IB = -0.5 mA			-0.25	V
Input voltage	Vi(on)	VCE = -0.2 V, IC = -5 mA	-2.1			V
	Vi(off)	VCE = -5 V, IC = -100 $\mu\text{A}$			-0.8	
Input resistance	R1		-30%	10	+30%	k $\Omega$
Resistance ratio	R1/R2		0.8	1.0	1.2	-

Note: 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

2. \*1 Pulse measurement

## Packing

Embossed type (Thermo-compression sealing) R specification : 10 000 pcs / reel

2010.3.3	2010.9.16	
Prepared	Revised	

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